

TOREX SEMICONDUCTOR LTD.
Quality Assurance Dept.

Composition Table

Product(Pb-free): XC9503xxxxAR-G

Typical Mass: 25 mg

Part name	Weight(mg)	Material name	Ratio(ppm)	CAS number
Silicon chip	1.492	Silicon	59700	7440-21-3
	-	Arsenic	3	7440-38-2
Leadframe	10.091	Copper	403600	7440-50-8
	0.025	Tin	1000	7440-31-5
	0.022	Zinc	900	7440-66-6
	0.025	Chromium	1000	7440-47-3
	0.556	Silver	22200	7440-22-4
Die attach	0.027	Silver	1100	7440-22-4
	0.009	Epoxy	400	—
Bonding wire	0.100	Gold	4000	7440-57-5
Resin	10.144	Silica	405800	60676-86-0
	0.754	Epoxy Resin	30100	—
	0.696	Phenol Resin	27800	—
Plating	1.058	Tin	42300	7440-31-5

* The component composition is based on the information provided by raw material vender.

* The mass of the IC and its fractions could be different due to the manufacturing conditions of materials.

* Any indication "-" in CAS number means "confidential."